

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2611cdd#pbf

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

(printed on: 2020-07-11 19:30:21)

TOTAL MASS (g) : 0.023095

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001091 | 1000000 | 47238.921875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.009711 | 975000 | 420474.0625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000239 | 24000 | 10348.3984375 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000003 | 300 | 129.896209717 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000007 | 700 | 303.091156006 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.009960 | 1000000 | 431255.4375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000455 | 1000000 | 19716.6289062 | | |
| | | External Plating Total: | | | | 0.000455 | 1000000 | 19716.6289062 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000225 | 1000000 | 9742.21484375 | | |
| Internal Plating Total: | | | | 0.000225 | 1000000 | 9742.21484375 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000613 | 750000 | 26542.1269531 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000204 | 250000 | 8832.94140625 | | |
| Die Attach Total: | | | | 0.000817 | 1000000 | 35375.0664062 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001362 | 130000 | 58972.8789062 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.009013 | 860000 | 390251.53125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000105 | 10000 | 4546.36767578 | | |
| | | Encapsulation Total: | | | | 0.010480 | 1000000 | 453770.75 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000067 | 1000000 | 2901.01538086 | | |
| | | | | | TOTAL MASS (g) : | 0.023095 | | |